

# Size-effects in time-dependent mechanics of AI-Cu MEMS

*Citation for published version (APA):* Bergers, L. I. J. C., Hoefnagels, J. P. M., & Geers, M. G. D. (2011). Size-effects in time-dependent mechanics of AI-Cu MEMS. In *Proceedings of Euromat 2011, 12-15 September 2011, Montpellier, France* (pp. D21-O-6-2-1694/1)

Document status and date: Published: 01/01/2011

### Document Version:

Publisher's PDF, also known as Version of Record (includes final page, issue and volume numbers)

### Please check the document version of this publication:

• A submitted manuscript is the version of the article upon submission and before peer-review. There can be important differences between the submitted version and the official published version of record. People interested in the research are advised to contact the author for the final version of the publication, or visit the DOI to the publisher's website.

• The final author version and the galley proof are versions of the publication after peer review.

• The final published version features the final layout of the paper including the volume, issue and page numbers.

Link to publication

#### General rights

Copyright and moral rights for the publications made accessible in the public portal are retained by the authors and/or other copyright owners and it is a condition of accessing publications that users recognise and abide by the legal requirements associated with these rights.

- · Users may download and print one copy of any publication from the public portal for the purpose of private study or research.
- You may not further distribute the material or use it for any profit-making activity or commercial gain
  You may freely distribute the URL identifying the publication in the public portal.

If the publication is distributed under the terms of Article 25fa of the Dutch Copyright Act, indicated by the "Taverne" license above, please follow below link for the End User Agreement:

www.tue.nl/taverne

#### Take down policy

If you believe that this document breaches copyright please contact us at:

openaccess@tue.nl

providing details and we will investigate your claim.

Topic Area	D Characterization and Modelling	D21-O-6-2
Торіс	D2 - Mechanical Characterisation Techniques	1694
Symposium	D21 - Macro/meso-mechanical characterization of materials and microstructural effects	
Session	6. Thin films, materials in electronics and MEMS, contacts	

# Size-effects in time-dependent mechanics of AI-Cu MEMS

# L. Bergers (Eindhoven University of Technology, Eindhoven, Netherlands), J. Hoefnagels, M. Geers

L. Bergers (Eindhoven Univ. of Technology, Dept. of Mech., NL,; Foundation for Fundamental Research on Matter, Utrecht, NL; Materials innovation institute (M2i), NL), <u>I.i.j.c.bergers@tue.nl</u>

J. Hoefnagels (Eindhoven Univ. of Technology, Dept. of Mech. Engg., P.O.Box 513, 5600MB, Eindhoven, NL)

M. Geers (Eindhoven Univ. of Technology, Dept. of Mech. Engg., P.O.Box 513, 5600MB, Eindhoven, NL)

## Abstract

Creep is a time-dependent deformation mechanism that affects the reliability of metallic MEMS [1]. Examples of metallic MEMS are RF-MEMS capacitors/switches, found in wireless/RF applications. The role of size-effects on creep in MEMS is not well understood. This precludes modeling for reliability of MEMS. To have a better understanding, first a novel micro-beam bending methodology is set up to study time-dependent deflection in Al-Cu alloy thin film micro-cantilever beams that are micro-fabricated in the same MEMS fabrication process as actual RF-MEMS devices. Second, measurements are performed where the effect of variations in size on the deflection behavior is studied.

Mechanical characterization of this behavior at the micro-scale is not trivial. Recently a suitable methodology has been developed to measure time-dependent deflections of  $\mu$ m-sized cantilevers [2,3]. A fully mechanical deflection-controlling mechanism is designed, a so-called micro-clamp. Combined with in-situ confocal profilometry, cantilever deflection is precisely controlled and measured. Following a period of prolonged constant deflection, time-dependent deflection recovery is measured once deflected cantilevers are released. Applying digital image correlation and kinematics-based averaging algorithms to the measured surface profiles corrects for various errors and yields a precision of < 7% of the surface roughness. Assuming a visco-elastic model, further analysis is then applied to extract basic quantities describing the deflection recovery behavior. This successful methodology will be briefly discussed.

With this methodology the effect of intrinsic, e.g. grain size, alloy structure, and extrinsic, e.g. structure size, on the deflection recovery behavior is measured. Alloy structure variations are achieved by aging Al-(1wt%)Cu thin metal films at elevated temperatures, whilst grain size variations are revealed using EBSD. First results show a remarkable yet clear trend that micro-cantilevers of aged alloys show more deflection recovery. These will be presented, alongside the effect of grain size. Finally, these insights will be discussed in light of the underlying dislocation and diffusion mechanisms.

[1] Van Spengen, Microelectron. Reliab, 2003

[2] Bergers, etal. Proc. 11th EurosimE, 2010

[3] Bergers, etal. Microelectron.Reliab. (accepted), 2011